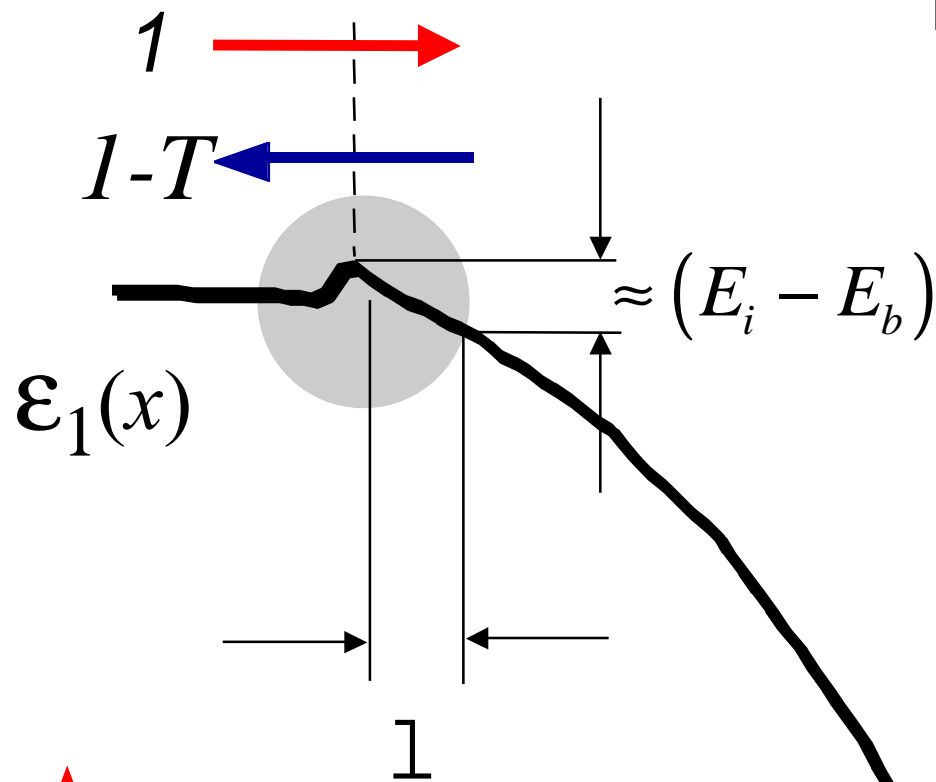


3. Scattering Theory of the MOSFET.....

computing T : high V_{DS}



$P(x_1)$: probability of returning to the source after scattering first at x_1

$x_1 < l$ $P(x_1)$ large

$x_1 > l$ $P(x_1)$ small

$$qV(l) \approx (E_i - E_b)$$

$$T \approx \frac{\lambda_o}{1 + \lambda_o}$$

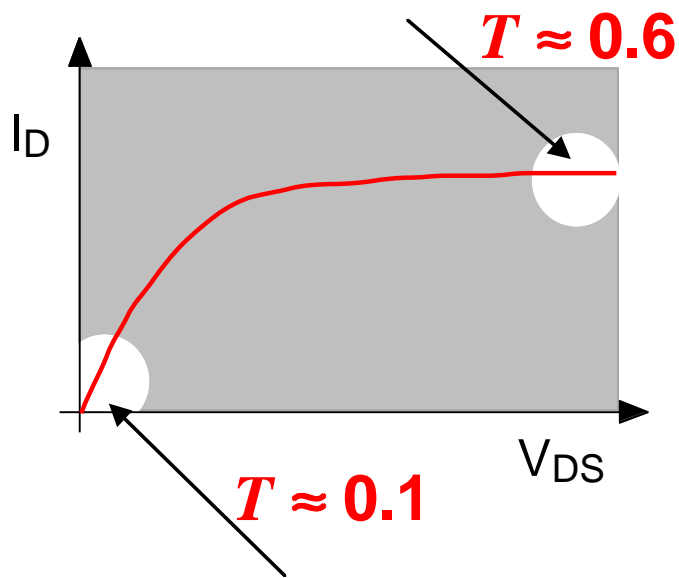


mobility is important for nanoscale FETs

3. Scattering Theory of the MOSFET.....

Landauer/McKelvey model

$$I_D = W C_{ox} v_T \left(\frac{T}{2-T} \right) (V_{GS} - V_T)$$



$$I_D = W C_{ox} \left(\frac{v_T / 2}{k_B T / q} \right) T (V_{GS} - V_T) V_{DS}$$

$$I_{DS} = W C_{ox} (V_{GS} - V_T) \tilde{v}_T \left(\frac{T}{2-T} \right) \times$$

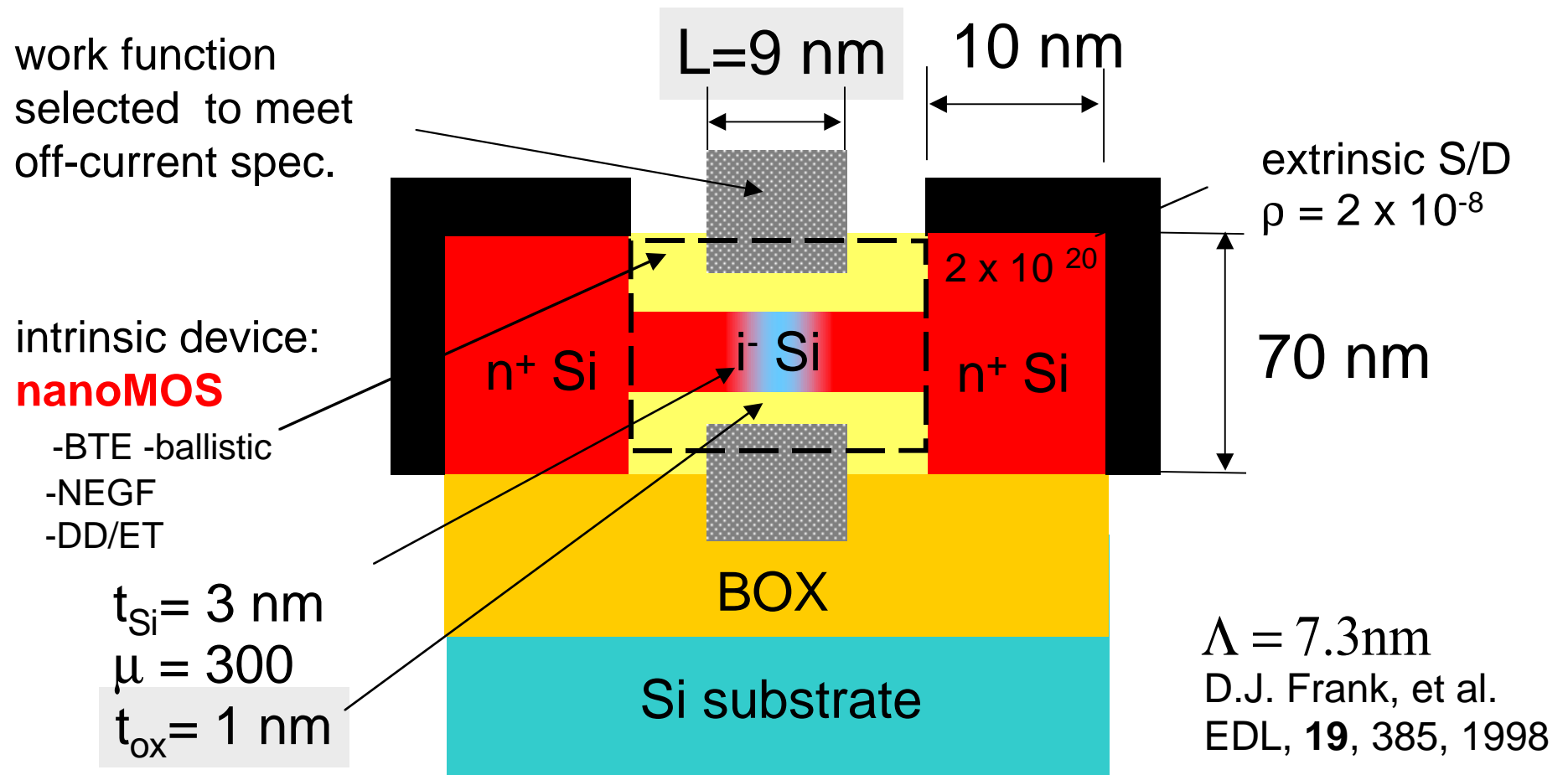
$$\left\{ \frac{1 - \frac{F_{1/2}(\eta_F - U_{DS})}{F_{1/2}(\eta_F)}}{1 + \left(\frac{T}{2-T} \right) \frac{\ln(1 + e^{\eta_F - U_{DS}})}{\ln(1 + e^{\eta_F})}} \right\}$$

$$T = \frac{\lambda_o}{1 + \lambda_o}$$

-
- scattering theory provides a clear picture of MOSFETs at the scaling limit:
 - source velocity is limited by thermal injection
 - velocity saturation occurs at the source
 - the scattering that matters occurs near the source
 - "mobility" is relevant to nanoscale MOSFETs

4. Design Issues for 10nm MOSFETs.....

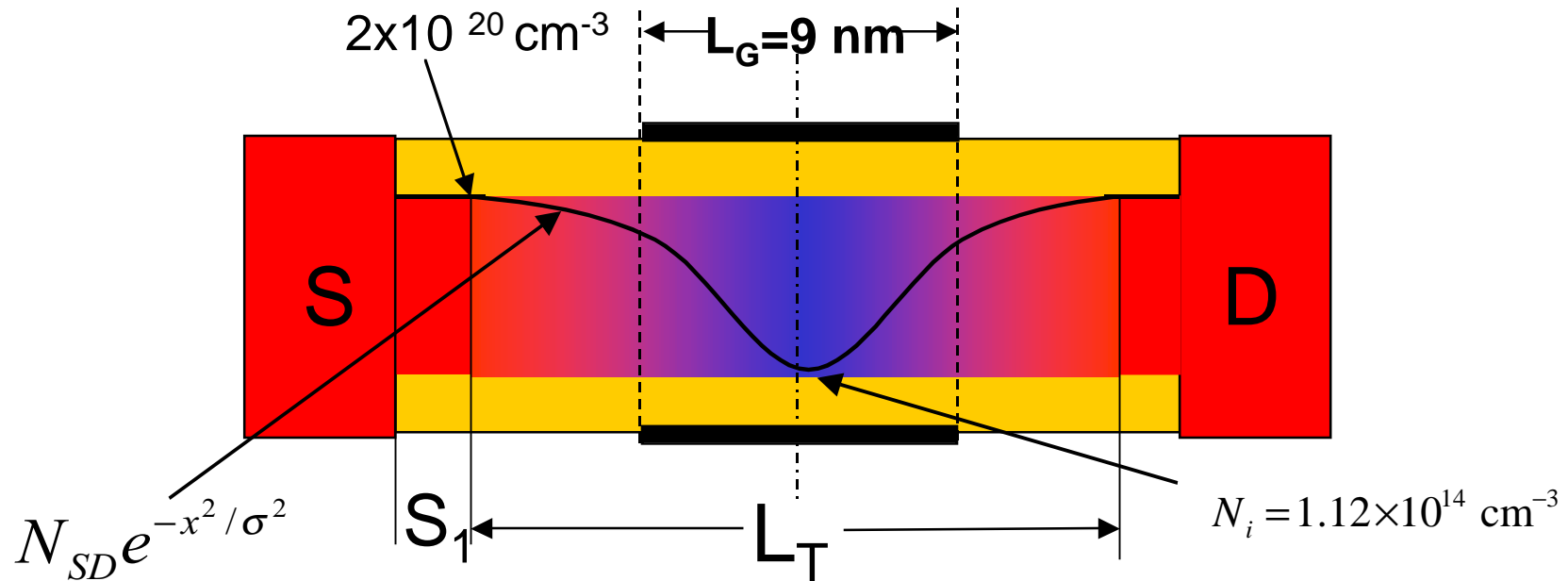
a numerical study



Taichi Su, J.P.Denton, G.W.Neudeck, *IEEE International SOI Conf*, Oct. 2000, pp. 110-111

4. Design Issues for 10nm MOSFETs.....

a numerical study



For a specified maximum doping, doping gradient, and I_{off} :

examine I_{on} , S, DIBL vs. L_T .

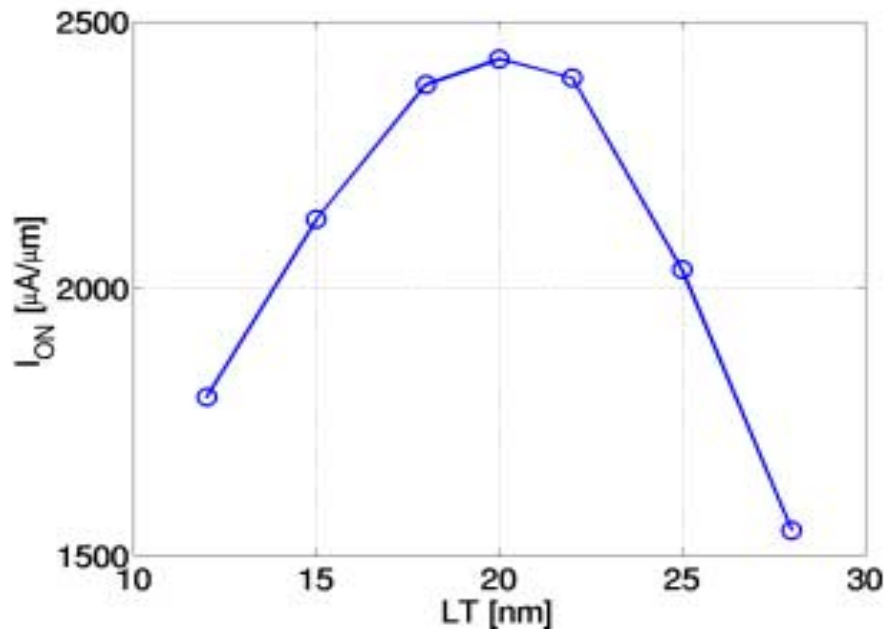
$$g \equiv \left| \frac{dx}{d \log_{10} N} \right|_{\text{at 1 dec point}} = 2 \text{ nm/dec}$$

$$\sigma = 2g \sqrt{\log_{10} e} = 2.64 \text{ nm}$$

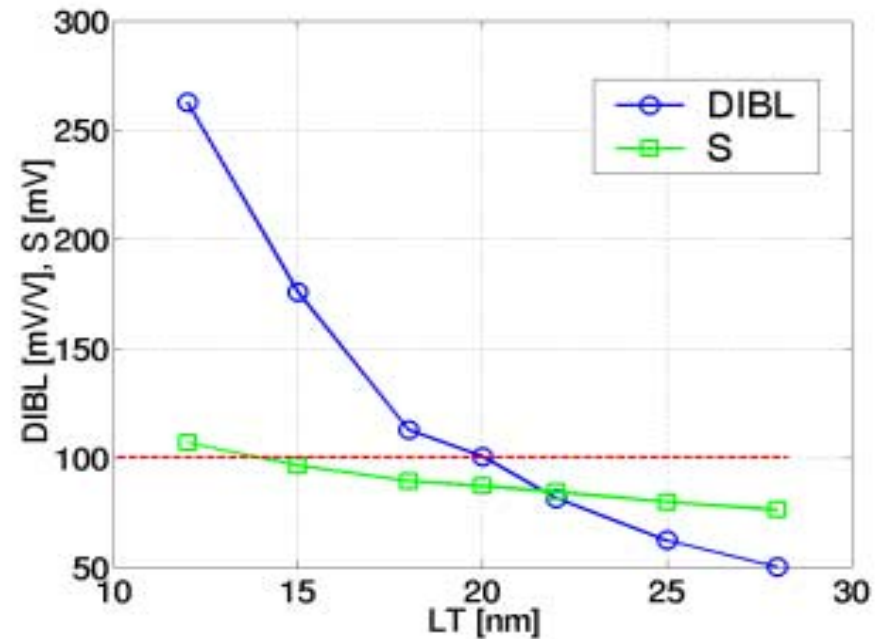
4. Design Issues for 10nm MOSFETs.....

a numerical study

Choose L_T to give the highest I_{ON} together with acceptable S and DIBL



I_{ON} vs. L_T , at $I_{off} \sim 10 \mu A/\mu m$

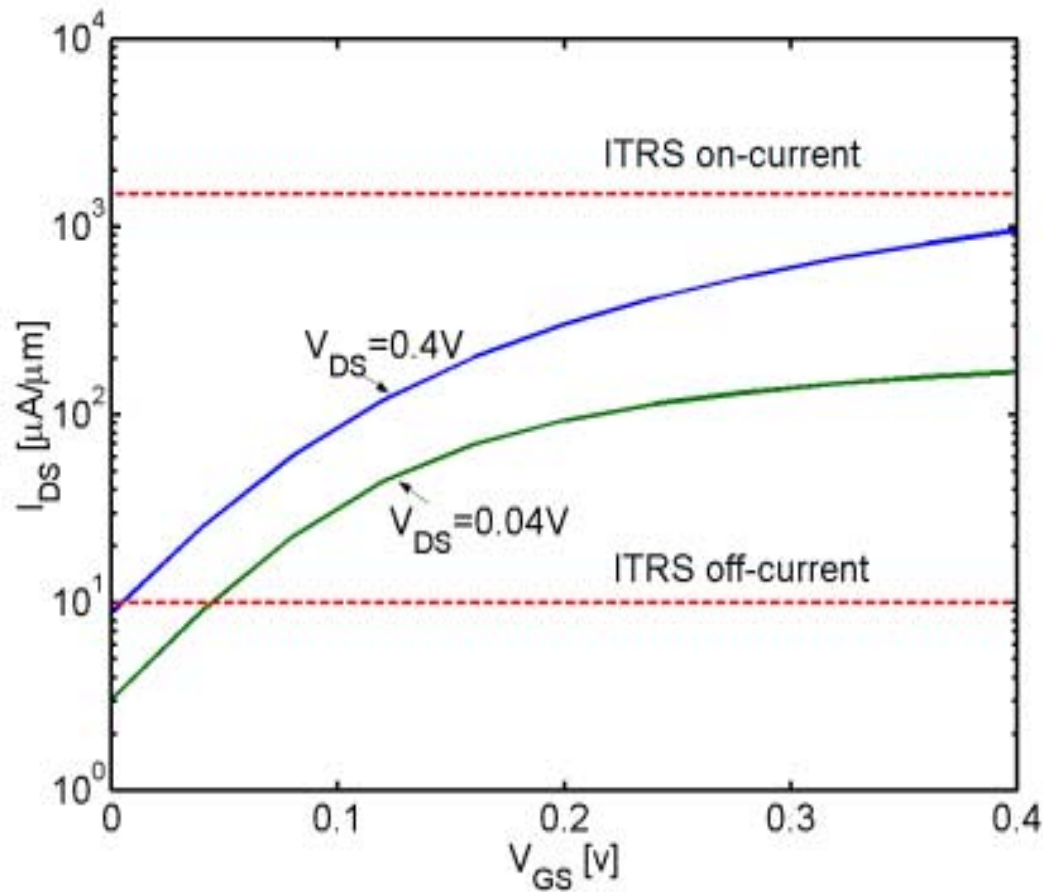


DIBL, S vs. L_T

$L_T = 20$ nm is the optimized value! (Gate Work Function is 4.18 eV.)

4. Design Issues for 10nm MOSFETs.....

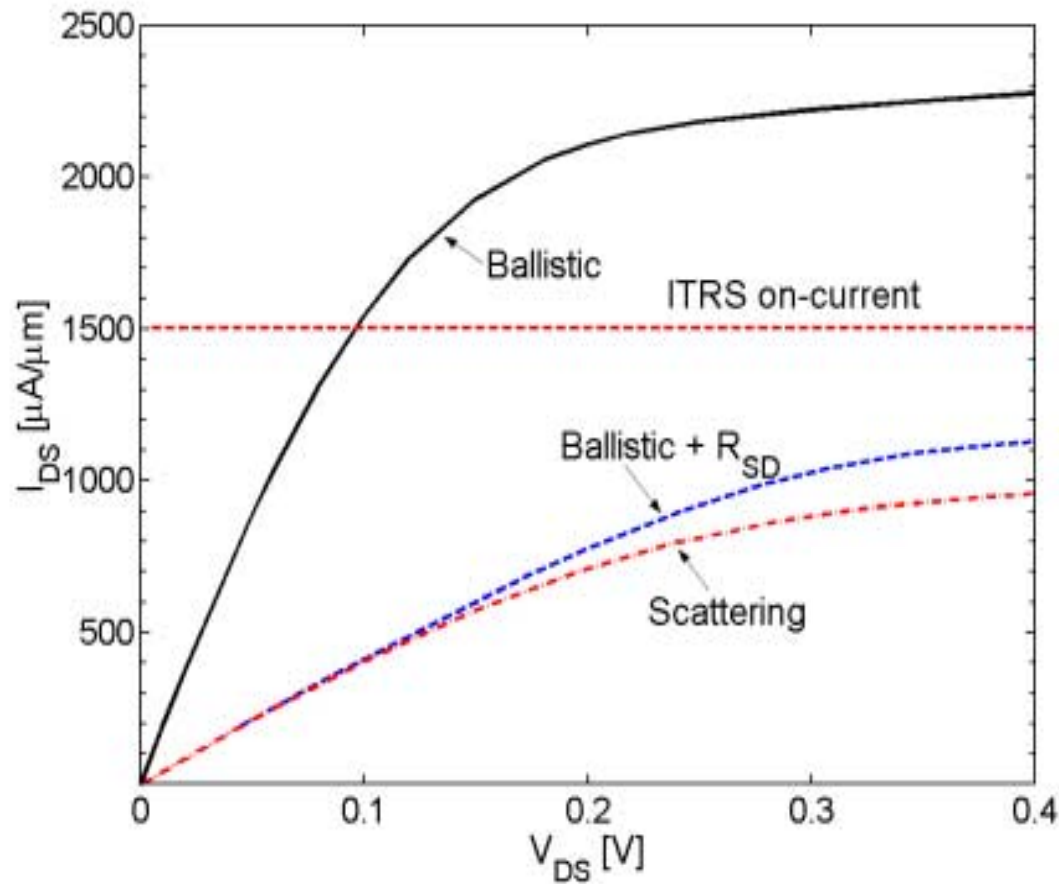
a numerical study



	Value	ITRS
$I_{on}(\mu\text{A}/\mu\text{m})$	960	1500
$I_{off}(\mu\text{A}/\mu\text{m})$	9	10
DIBL(mV/V)	111	-----
S(mV/dec)	87	75
$R_{SD}(\Omega\text{-}\mu\text{m})$	200	80
V_{DD}/I_{on}	417	267
τ (ps)	0.16	0.15

4. Design Issues for 10nm MOSFETs.....

series resistance



$$R_{SD} = 2(R_C + R_{ext})$$

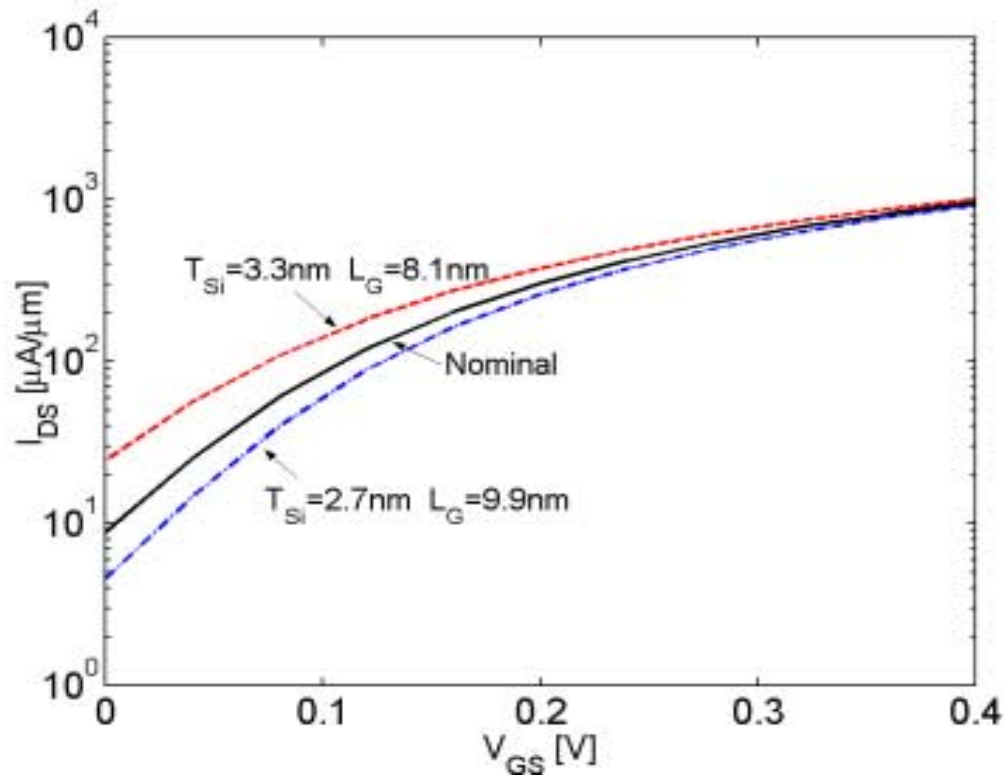
$$R_C \approx \frac{\rho_C}{A_C} = 25 \Omega$$

$$R_{ext} \approx 25 \Omega + 50 \Omega$$

(tip)

4. Design Issues for 10nm MOSFETs.....

parameter variation



$$T_{Si} = 3 \text{ nm} \pm 0.3 \text{ nm}$$

$$L_G = 9 \text{ nm} \pm 0.9 \text{ nm}$$

$$4.5 < I_{off} < 25 \mu\text{A}/\mu\text{m}$$

$$920 < I_{on} < 1006 \mu\text{A}/\mu\text{m}$$

$$40 < I_{on}/I_{off} < 205$$

4. Design Issues for 10nm MOSFETs.....

what limits the on-current?

$$I_D/W = Q_i(0) \langle v(0) \rangle$$

1) $Q_i(0)$:

fundamental limits:

source exhaustion:

$$Q_i/q \approx 6 \times 10^{13} \text{ cm}^{-2} \quad (N_D t_{Si})$$

insulator field

$$Q_i/q \approx 4 \times 10^{13} \text{ cm}^{-2}$$

practical limit:

$$C_{eff} (V_{DD} - V_T)$$

$$Q_i/q \approx 0.8 \times 10^{13} \text{ cm}^{-2}$$

$$C_{eff} (V_{DD} - V_T - I_D R_S)$$

$$Q_i/q \approx 0.5 \times 10^{13} \text{ cm}^{-2}$$

2) $\langle v(0) \rangle$:

bandstructure, E_F limit:

$$\langle v(0) \rangle \approx 1.8 \times 10^7 \text{ cm/s}$$

practical limit: (scattering)

$$\langle v(0) \rangle \approx 1.1 \times 10^7 \text{ cm/s}$$

3) **Result:**

$$I_D(on) = q(0.5 \times 10^{13})(1.2 \times 10^7) = 960 \mu\text{A}/\mu\text{m}$$